

SPECIFICATION

REFOND P/N

RF-A3E27-W60H-B3

R&D

Mass Production

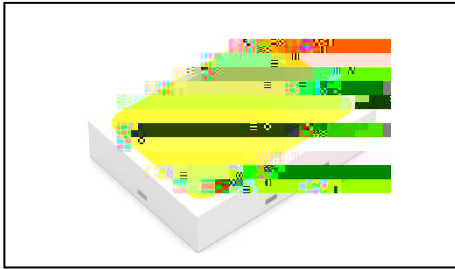
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1. Description

1.1 General Description



The White LED, which was fabricated by using a blue chip and the phosphor.

Product Package:2.7mmX2.0mmX0.6mm.

LED

2.7mmX2.0mmX0.6mm

1.2 Features

EMC Package.EMC

Extremely wide viewing angle.

Suitable for all SMT assembly and solder process. SMT

Available on tape and reel.

Moisture sensitivity level: Level 2. Level2

RoHS compliant. RoHS

Qualifications: The product qualification test plan is based on the guidelines of AEC-Q102
 Stress Test Qualification for Automotive Grade Discrete Semiconductors

AEC-Q102

1.3 Application

Automotive Lighting Interior and Exterior.

1.4 Package Dimension

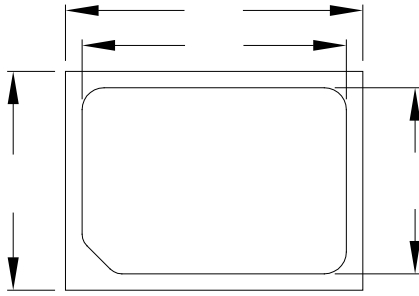


Fig.1-1 Top View

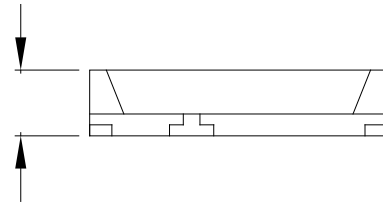


Fig.1-2 Side View

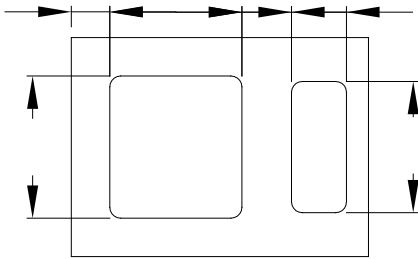


Fig.1-3 Bottom View

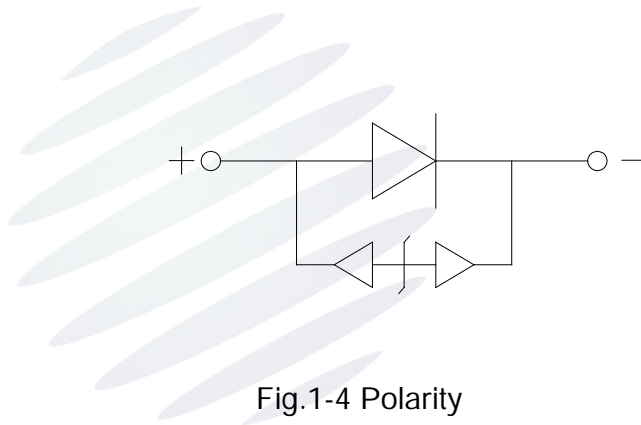


Fig.1-4 Polarity

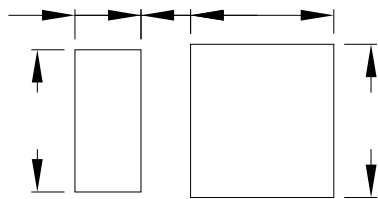


Fig.1-5 Soldering Patterns

Notes

1. All dimensions units are millimeters.
2. All dimensions tolerances are $\pm 0.2\text{mm}$ unless otherwise noted.

± 0.2

1.5 Product Parameters

Table 1-1 Electrical / Optical Characteristics at Ts=25°C

| Item | Symbol | Test Condition | Value | | | Unit |
|---------------------|--------------------|--------------------|-------|------|------|---------------|
| | | | Min. | Typ. | Max. | |
| Forward Voltage | V_F | $I_F=350\text{mA}$ | 2.8 | --- | 3.4 | V |
| Reverse Current | I_R | $V_R=5\text{V}$ | --- | --- | 10 | μA |
| Luminous Flux | | $I_F=350\text{mA}$ | 105 | --- | 160 | lm |
| Viewing Angle | | $I_F=350\text{mA}$ | --- | 120 | --- | deg |
| Thermal Resistance. | $R_{\text{THJ-S}}$ | $I_F=350\text{mA}$ | --- | 14 | 21 | /W |
| | $R_{\text{THJ-S}}$ | $I_F=350\text{mA}$ | --- | 9 | 13 | /W |

Table 1-2 Absolute Maximum Ratings at Ts=25°C

| Parameter | Symbol | Rating | Units |
|-------------------------------|-----------|------------|-------|
| Power Dissipation | P_D | 1428 | mW |
| Forward Current | I_F | 420 | mA |
| Peak Forward Current | I_{FP} | 700 | mA |
| Reverse Voltage | V_R | 5 | V |
| Electrostatic Discharge (HBM) | E_{SD} | 8000 | V |
| Operating Temperature | T_{OPR} | -40 ~ +125 | |
| Storage Temperature | T_{STG} | -40 ~ +125 | |
| Junction Temperature | T_J | 150 | |

Notes

1. 1/10 Duty cycle, 10ms pulse width. 10ms, 1/10.
2. The above forward voltage measurement allowance tolerance is $\pm 0.1V$. $\pm 0.1V$.
3. The above color coordinates measurement allowance tolerance is ± 0.005 . ± 0.005 .
4. The above luminous flux measurement allowance tolerance $\pm 10\%$. $\pm 10\%$.
- 5.



Fig. 1-6 The C.I.E Chromaticity Diagram CIE

Table 1-4

| BIN CODE | CIE-X1 | CIE-Y1 | CIE-X2 | CIE-Y2 | CIE-X3 | CIE-Y3 | CIE-X4 | CIE-Y4 |
|----------|--------|--------|--------|--------|--------|--------|--------|--------|
| VM1 | 0.3150 | 0.2995 | 0.3115 | 0.3212 | 0.3268 | 0.3371 | 0.3282 | 0.3162 |
| VM2 | 0.3210 | 0.3060 | 0.3190 | 0.3280 | 0.3340 | 0.3420 | 0.3340 | 0.3230 |
| VM3 | 0.3270 | 0.3140 | 0.3270 | 0.3360 | 0.3420 | 0.3490 | 0.3410 | 0.3300 |
| VM4 | 0.3340 | 0.3230 | 0.3340 | 0.3420 | 0.3480 | 0.3535 | 0.3480 | 0.3370 |
| VM5 | 0.3165 | 0.3180 | 0.3140 | 0.3380 | 0.3298 | 0.3525 | 0.3302 | 0.3307 |
| VM6 | 0.3223 | 0.3260 | 0.3209 | 0.3461 | 0.3378 | 0.3615 | 0.3368 | 0.3368 |

1.7 Typical Optical Characteristics Curves

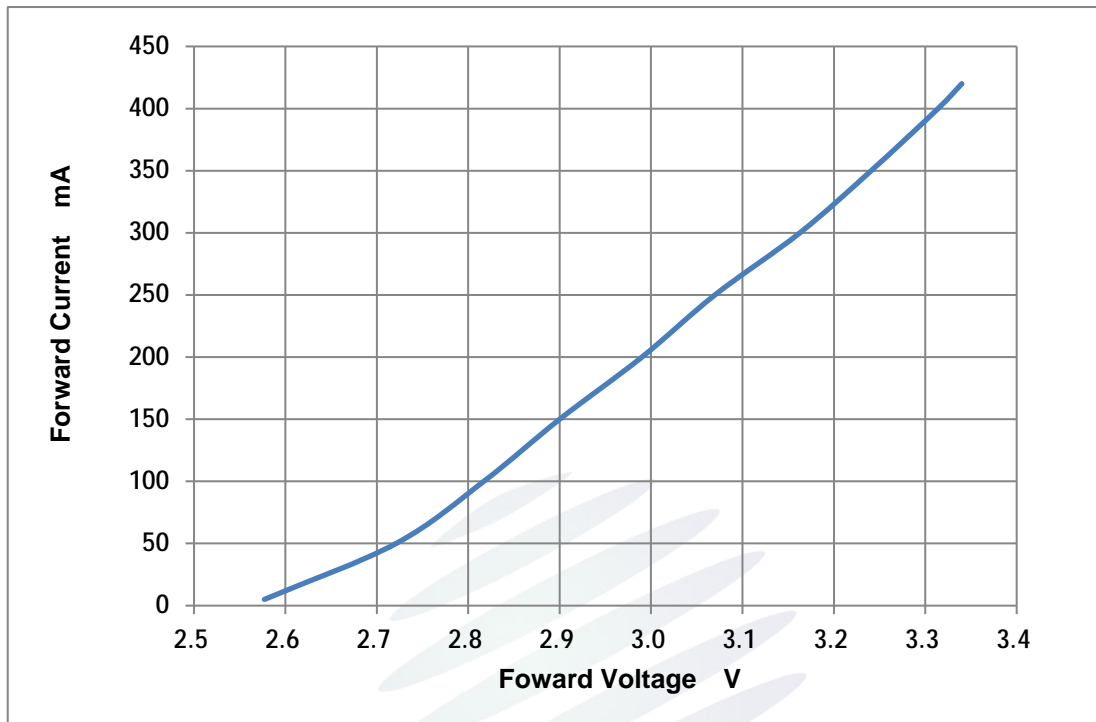


Fig. 1-7 Forward Voltage Vs Forward Current

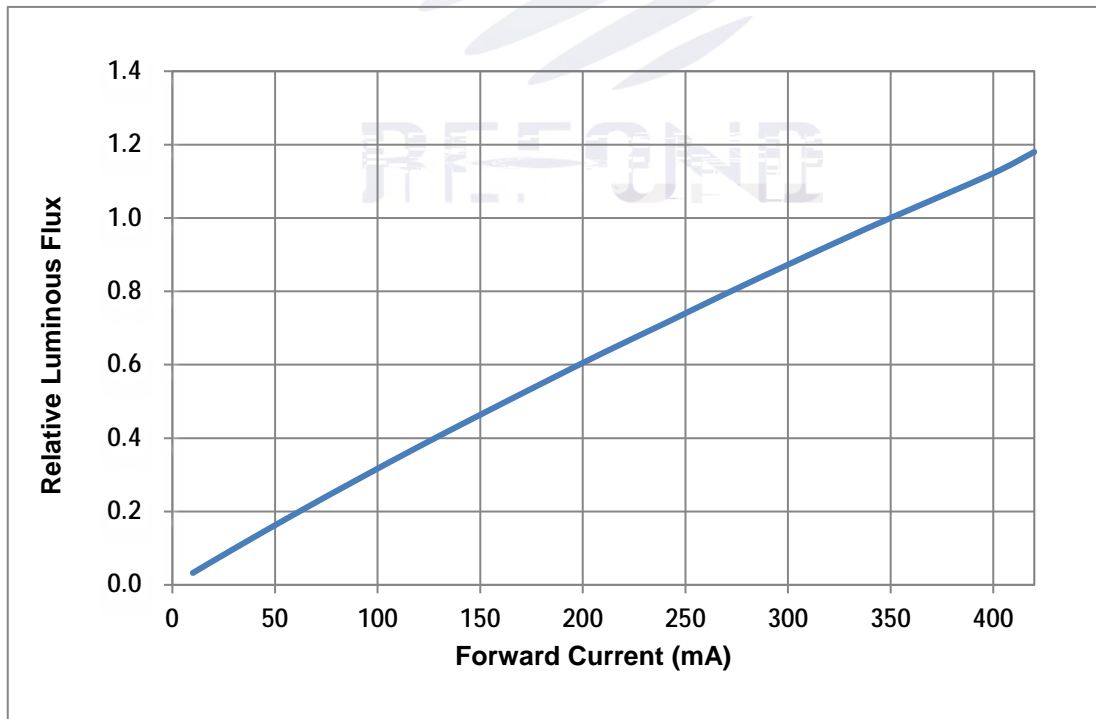


Fig. 1-8 Forward Current Vs Relative Luminous Flux

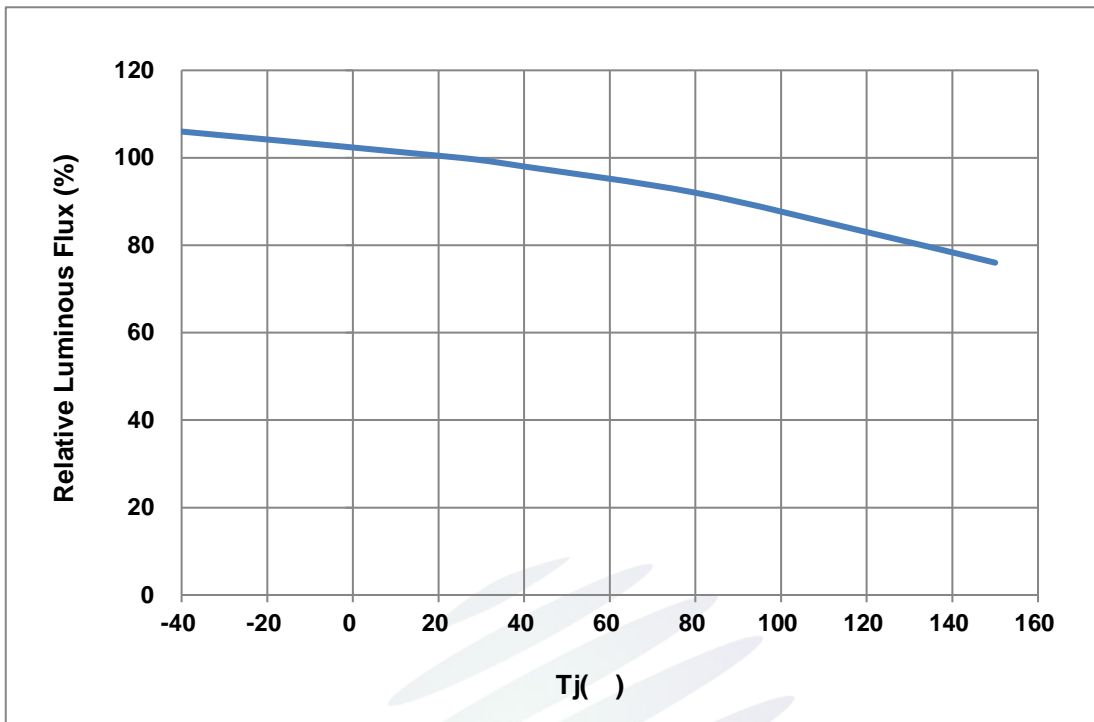


Fig. 1-9 Junction Temperature Vs Relative Luminous Flux

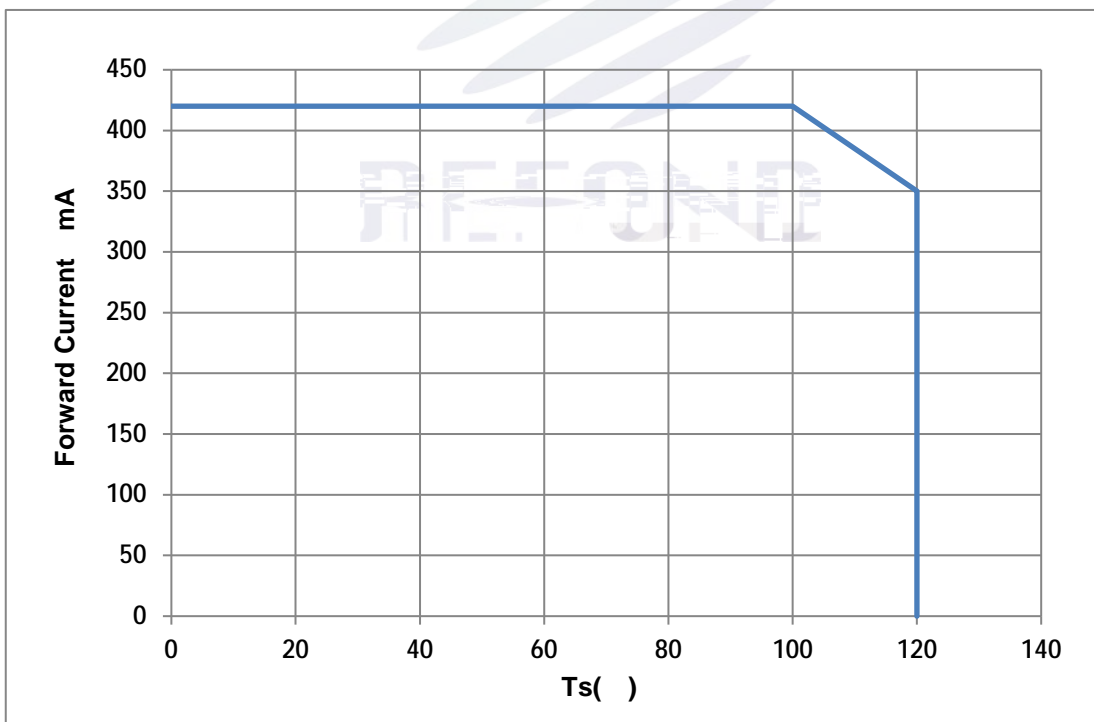


Fig. 1-10 Solder Temperature Vs Forward Current

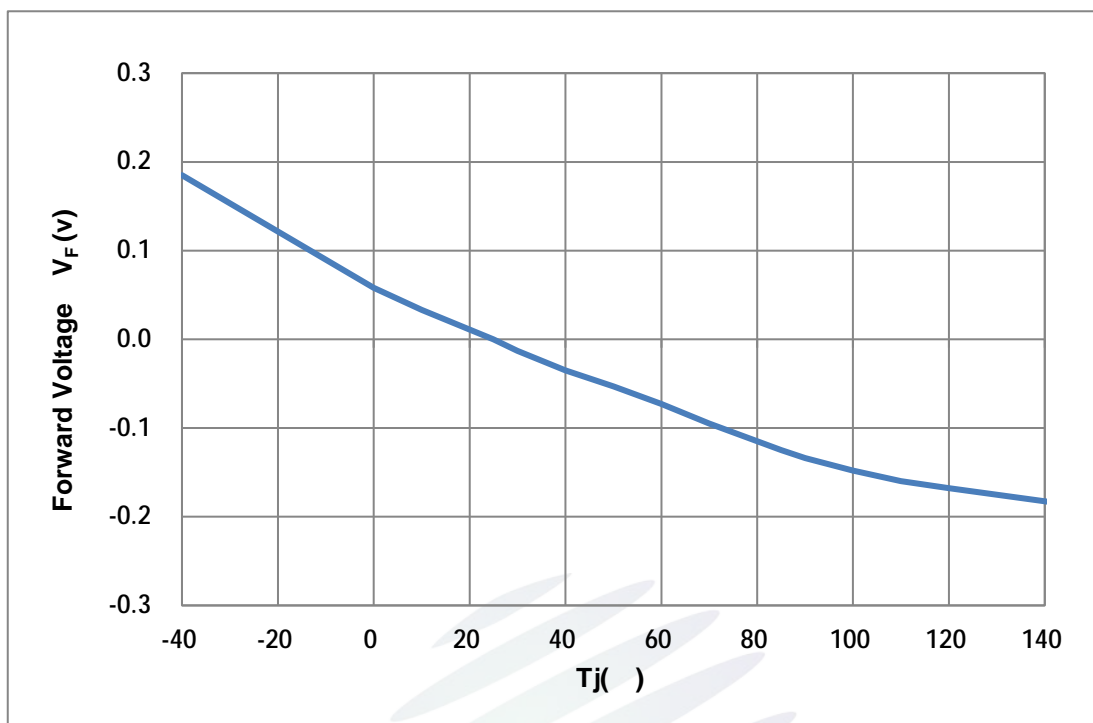


Fig. 1-11 Voltage Shift Vs Junction Temperature

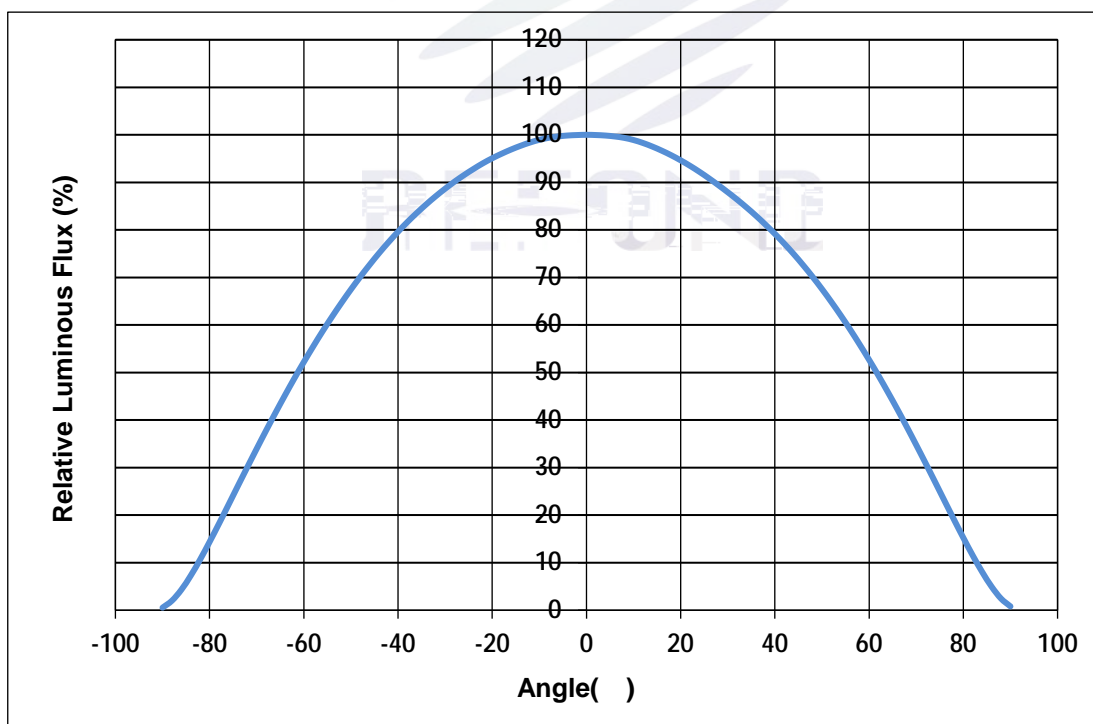


Fig. 1-12 Radiation Diagram

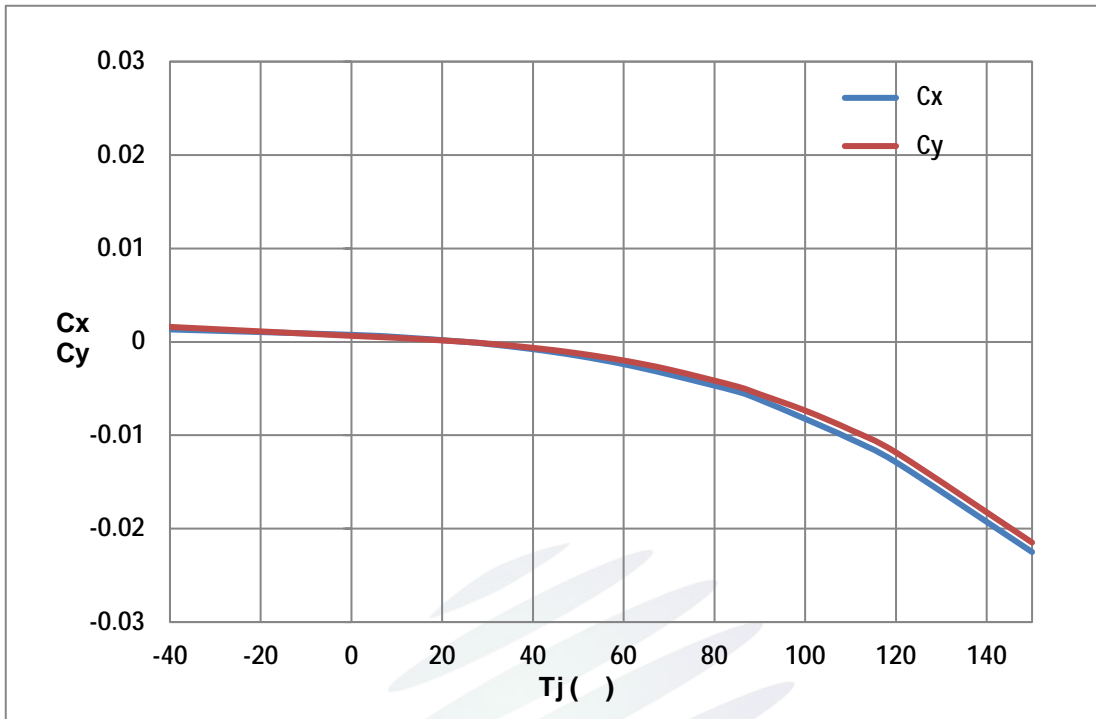


Fig. 1-13 Chromaticity Coordinate Shift Vs Junction Temperature

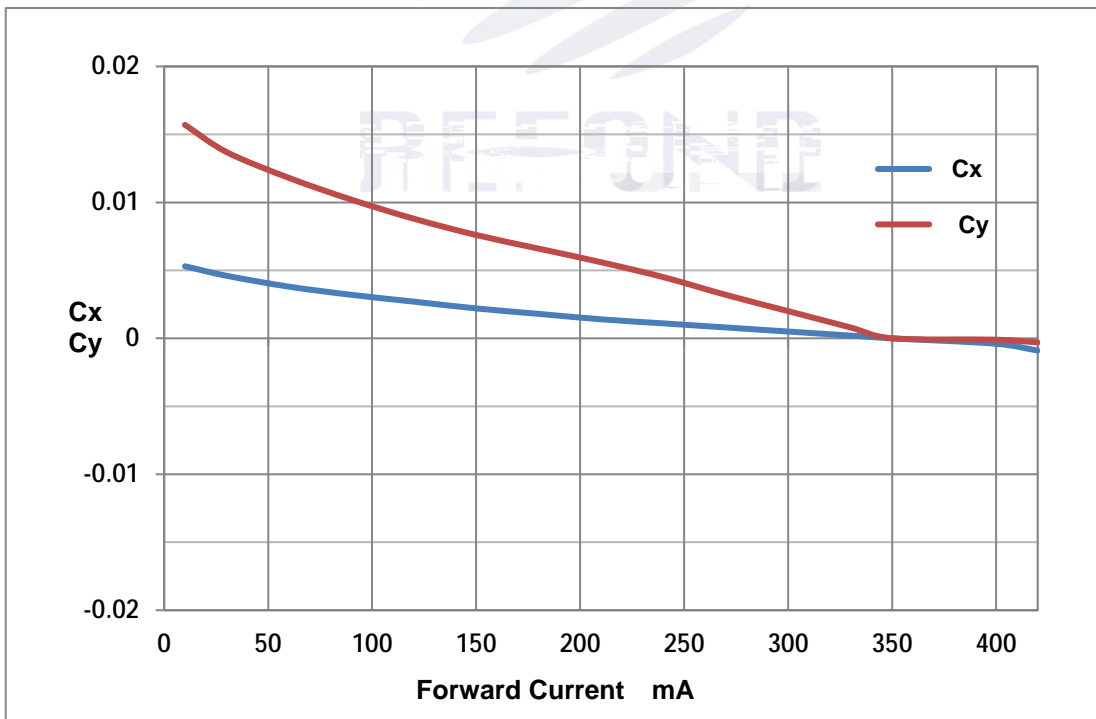


Fig. 1-14 Chromaticity Coordinate Shift Vs Forward Current

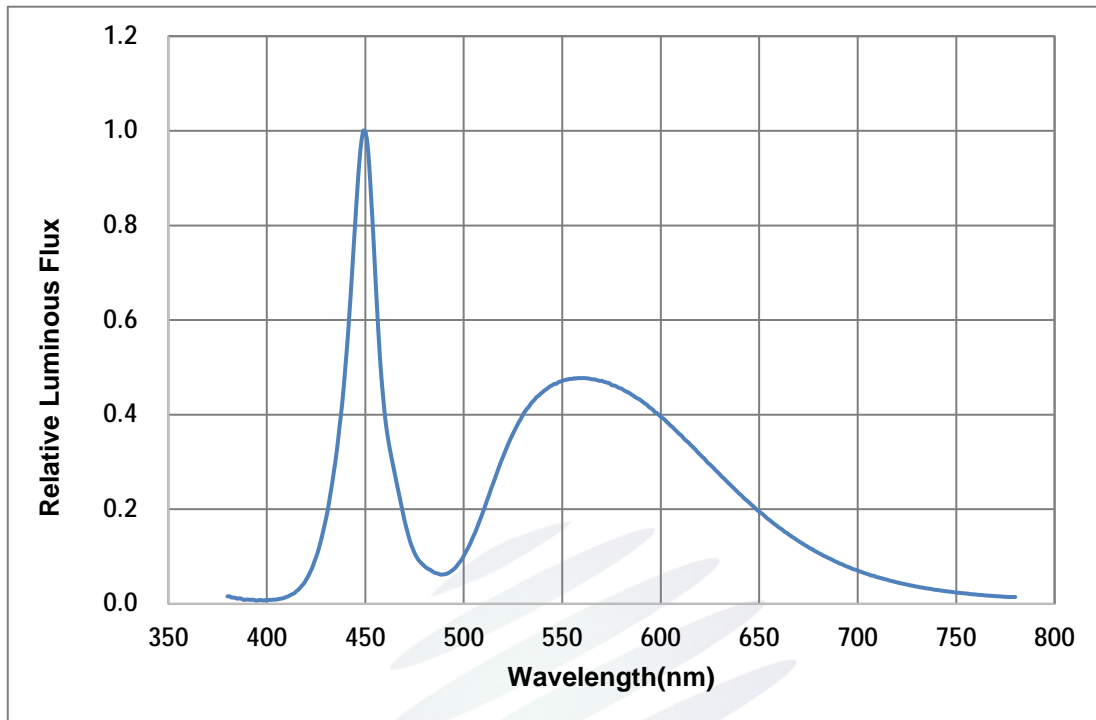


Fig. 1-15 Spectrum Distribution

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2.1.3 Label Form Specification

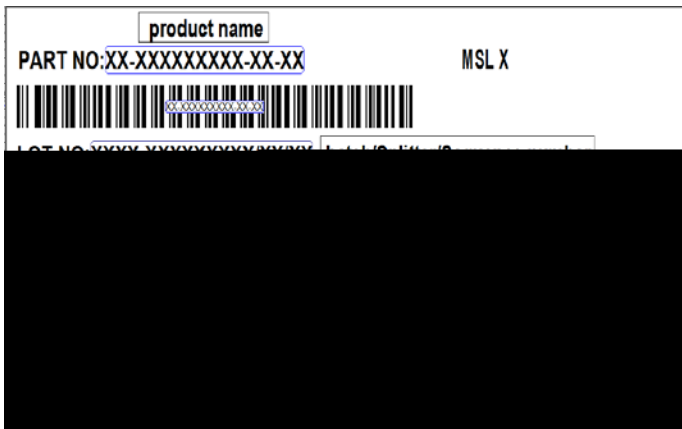


Fig. 2-3 Label Form Specification

Table 2-2 Specification

| | |
|----------------|------------------|
| PART NO. | Part Number |
| SPEC NO. | Spec Number |
| LOT NO. | Lot Number |
| BIN CODE | Bin Code |
| | Luminous flux |
| XY | Chromaticity Bin |
| V _F | Forward Voltage |
| WLD | Wavelength |
| QTY | Packing Quantity |
| DATE | Made Date |

2.2 Moisture Resistant Packing

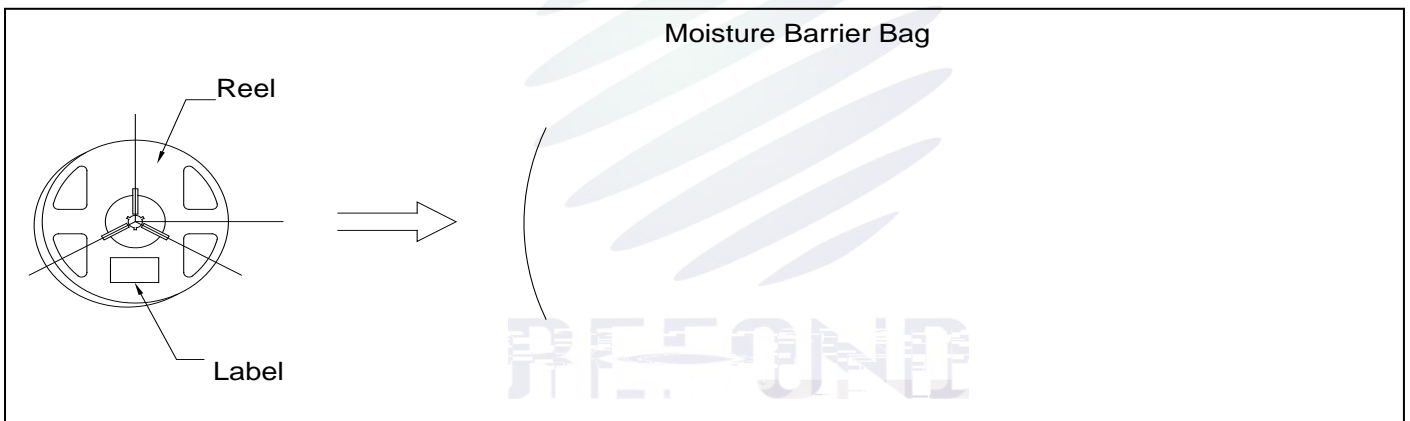


Fig.2-4Moisture Resistant Packing

2.3 Cardboard Box

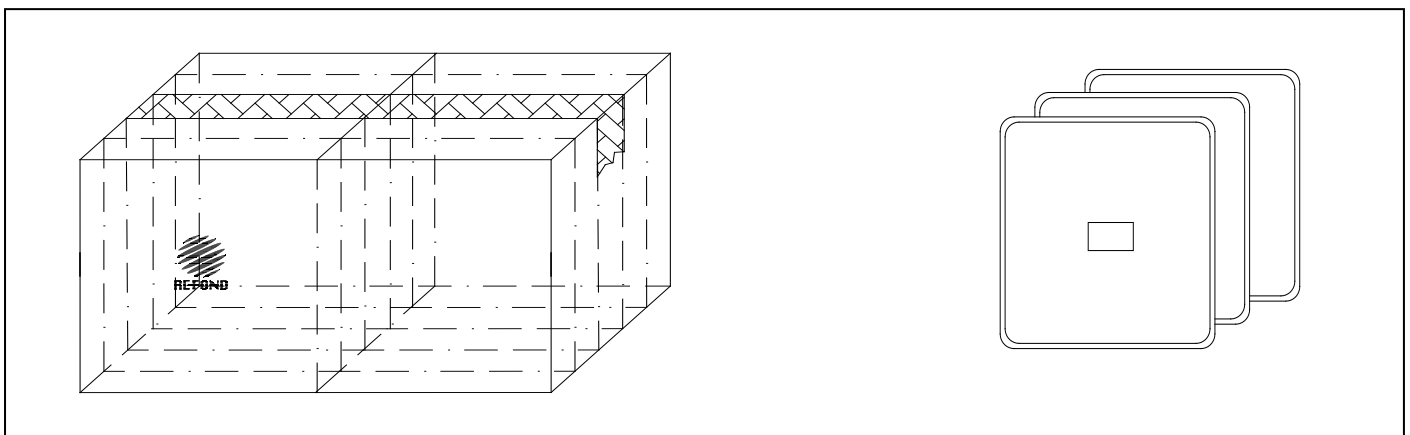


Fig.2-5Cardboard Box

2.4 Reliability Test Items And Conditions

Table 2-3 Reliability Test Items And Conditions

| Test Items | Ref.Standard | Test Condition | Time | Quantity | Ac/Re / |
|---------------------------------------------|------------------------|-------------------------------|------------|----------|------------|
| Reflow | JESD22-B106 | Temp:260 max T=10 sec | 2times | 20pcs. | 0/1 |
| MSL2 2 | JESD22-A113 | 85 / 60%RH | 168 hrs. | 20pcs. | 0/1 |
| Thermal Shock | JEITAED-4701 300307 | -40 15min 10s 125 15min | 1000 cycle | 20pcs. | 0/1 |
| Life Test | JESD22-A108 | Ta=105 IF=350mA | 1000hrs. | 20pcs. | 0/1 |
| High Temperature High Humidity Life Test | JESD22-A101 | 85 / 85%RH IF=350mA | 1000hrs. | 20pcs. | 0/1 |

2.5 Criteria For Judging Damage

Table 2-4Criteria For Judging Damage

| Test Items | Symbol | Test Condition | Criteria For Judgement | |
|-----------------|--------|--------------------|------------------------|-------------|
| | | | Min. | Max. |
| Forward Voltage | V_F | $I_F=350\text{mA}$ | - | U.S.L*)x1.1 |
| Reverse Current | I_R | $V_R = 5V$ | - | U.S.L*)x2.0 |
| Luminous Flux | | $I_F=350\text{mA}$ | L.S.L*)x0.7 | - |

Notes

- 1.U.S.L: Upper standard level L.S.L: Lower standard level
- 2.The above reliability tests is based on the verification of a single/strip LED of Refond's existing experimental platform,the reliability experiment was taken under good heat dissipation conditions. when customers applies the LED to the series and parallel circuit, should take consideration of all the factors such as the current, voltage distribution, heat dissipation and others. / LED
LED
3. The technical information shown in the data sheets is limited to the typical characteristics and circuit examples of the referenced products. It does not constitute the warranting of industrial property nor the granting of any license.

3 SMT Reflow Soldering Instructions SMT

3.1 SMT Reflow Soldering Instructions SMT

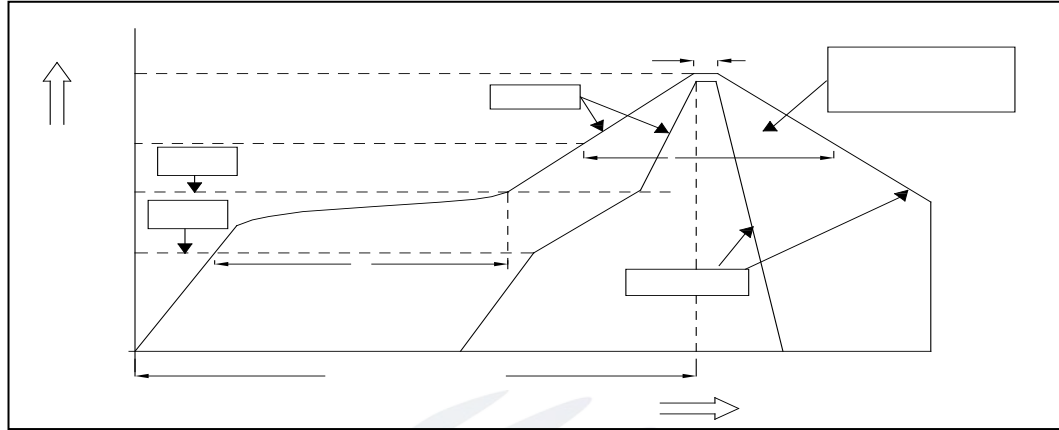


Fig.3-1 SMT Reflow Soldering Instructions SMT

Table 3-1 Reflow parameters

| | | |
|---------------------------------------------------------------------------------|---------------------------------|-------------------|
| Average temperature rise speed | T_{smax} T_P | 3 °C/ Max 3 °C/ s |
| Preheating: minimum temperature | (T_{smin}) | 150 °C |
| Preheating: Max temperature | (T_{smax}) | 200 °C |
| Preheating: Time | T_{smin} T_{smax} | 60 - 120 60s-120s |
| Time limited to maintain high temperature: the temperature (T_L) | | 217 °C |
| Time limited to maintain high temperature: The Time (t_L) | | 60 Max 60s |
| Peak /Classification of temperature: / (T_P) | | 260 °C |
| Time limit classification of peak temperature time (t_p) | | 10 Max 10s |
| (T_P) 5 °C Hold time within 5 °C with the actual peak temperature (T_P) | | 30 Max 30s |
| Cooling speed | | 6 °C/ Max 6 °C/ s |
| 25 °C | Needed time from 25 °C to T_P | 8 Max 8 minutes |

4. Handling Precautions



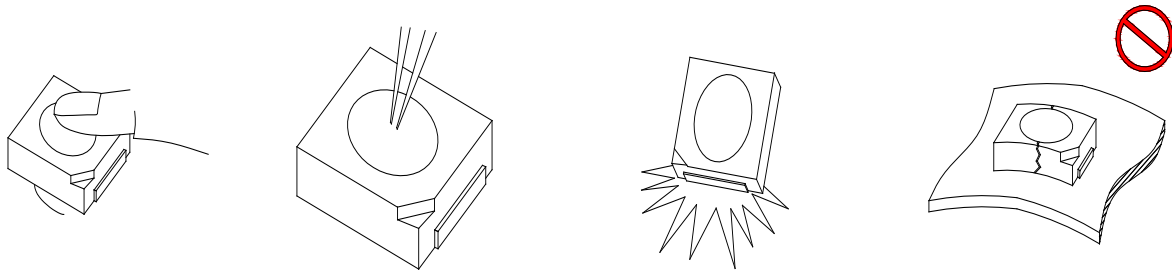


Fig 4-1Cautions

(5) In designing a circuit, the current through each LED can not exceed the absolute maximum rating specified for each LED. In the mean while, resistors for protection should be applied, other wise slight voltage shift will cause big current change, burn out may happen. The driving circuit must be designed to allow forward voltage only when it is ON or OFF. If the reverse voltage is applied to LED, migration can be generated resulting in LED damage.

LED

LED

(6) Thermal Design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decreased, Color change and so on. Please consider the heat generation of the LEDs when making the system design.

LED

(7) Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust, requiring special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of components. Refond suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or resin. Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause damage to the LED.

LED



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Declare

This specification is written both in English and in Chinese and the latter is formal.